L Number	Hits	Search Text	DB	Time stamp
1	13	Drussel near Zane.inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 14:07
2	387	"Singulation methods"and opening and separating near axis	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 14:23
3	5	"Singulation methods"and opening and separating near axis and cutting near tool	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 14:23
-	2	6664480.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 14:07
04-M+	25	("3780431"   "4316320"   "4426773"   "4532839"   "4621552"   "4742615"   "4791721"   "4926546"   "5311407"   "5448451"   "5483857"   "5488886"   "5521430"   "5652185"   "5773764"   "5831218"   "5854741"   "5886398"   "5894648"   "5960961"   "6047470"   "6114189"   "6239380"   "6246015"   "6342727").PN.	USPAT	2004/06/22 10:14
وابتراع	3	"Singulation methods" and 29/\$.ccls. and 174/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 10:16
-	99	"Singulation methods"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22
-	8476	"Singulation methods"and (74/250; 174/260; 174/261; 361/760; 361/79E; 361/719; 361/777; 361/846; 29/841; 428/901).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 14:21
-	2	"Singulation methods" and (74/250; 174/260; 174/261; 361/760; 361/79E; 361/719; 361/777; 361/846; 29/841; 428/901).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 10:22

-	4	"Singulation methods" and (174/250;	USPAT;	2004/06/22
1		174/260 ; 174/261 ; 361/760 ; 361/79E ;	US-PGPUB;	10:23
İ		361/719; 361/777 ; 361/846 ; 29/841 ;	EPO; JPO;	
		428/901).ccls.	DERWENT;	
			IBM_TDB	
,	3	"Singulation methods" and (174/250;	USPAT;	2004/06/22
		174/260 ; 174/261 ; 361/760 ; 361/79E ;	US-PGPUB;	10:23
		361/719; 361/777 ; 361/846 ; 29/841 ;	EPO; JPO;	
İ		428/901).ccls. and 29/\$.ccls.	DERWENT;	
			IBM TDB	

	Title	Current OR
1	Use of a reference fiducial on a semiconductor package to monitor and control a singulation method	438/401
2	Singulation methods and substrates for use with same	29/846
3	Method for determining the location of a droplet on a component	438/14
4	Use of a reference fiducial on a semiconductor package to monitor and control a singulation method	438/460
5	Singulation methods and substrates for use with same	
6	Method for establishing reference coordinates for a point on a component	438/16
7	Use of a reference fiducial on a semiconductor package to monitor and control a singulation method	257/708
8	Singulation methods and substrates for use with same	174/255
9	Method for determining the concentration of contamination on a component	438/14
10	Method for establishing reference coordinates for a point on a component	438/14
11	Singulation methods and substrates for use with same	174/250
12	Singulation methods	29/847

	Title	Current OR
13	Apparatus for establishing reference coordinates for a point on a component	118/712

	Current XRef	
1	438/462	
2	174/250; 174/255; 29/831	
3		
4	438/401	
5	174/268; 257/E23.004	
6		
7	257/797	
8	257/E23.004; 29/846; 361/771	
9		
10		
11	257/E23.004; 29/841; 29/846; 361/719; 361/766; 361/792; 428/901	
12	29/412; 29/415; 29/846; 83/35	